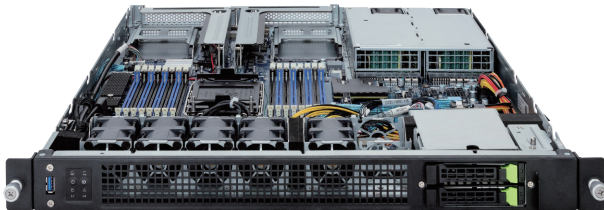


E163-S30-AAG1

Edge Server - 1U UP 2-Bay Gen4 NVMe/SATA

intel
XEON



Features

- Single 5th/4th Gen Intel® Xeon® Scalable Processors
- Single Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 16 x DIMMs
- Dual ROM Architecture supported
- 1 x 1Gb/s LAN port via Intel® I210-AT
- 2 x 2.5" Gen4 NVMe/SATA/SAS hot-swappable bays
- 1 x M.2 slot with PCIe Gen3 x4 interface
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP 3.0 Gen5 x16 slots
- 1+1 850W 80 PLUS Titanium redundant power supplies

Application

Edge, Networking, Hybrid/Private Cloud Server...

Specification

Dimensions	1U (W438 x H43.5 x D520 mm)	I/O Ports	Front: 1 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x RJ45, 1 x MLAN Internal: 1 x TPM header, 1 x VROC connector
Motherboard	MS33-DC0	Power Supply	1+1 850W 80 PLUS Titanium redundant power supplies AC Input: 100-240V
CPU	5th/4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Single processor, TDP up to 350W	System Management	ASPEED® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
Socket	1 x LGA 4677 (Socket E)	OS Compatibility	Windows Server 2019 / 2022 RHEL 8.6 / 8.7 / 8.8 / 8.9 / 8.10 / 9.0 / 9.1 / 9.2 / 9.3 / 9.4 SLES 15 SP4 / SP5 / SP6 Ubuntu 22.04 / 22.04.1 / 22.04.2 / 22.04.3 / 22.04.4 / 24.04 LTS VMware ESXi 7.0 Update 3o / 8.0 Update 1, Update 2, Update 3 Citrix Hypervisor 8.2 LTSR CU1
Chipset	Intel® C741 Chipset	System Fans	5 x 40x40x56mm (30,000rpm)
Memory	16 x DIMM slots, 8-Channel DDR5 memory RDIMM up to 96GB; 3DS RDIMM up to 256GB Memory speed: Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC)	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
LAN	1 x 1Gb/s LAN port (1 x Intel® I210-AT) - Supports NCSI function 1 x 10/100/1000 Mbps Management LAN	Packaging Content	1 x E163-S30-AAG1, 1 x CPU heatsink, 3 x Carrier clips, 1 x Mini-DP to D-Sub cable Packaging Dimensions: 989 x 594 x 279 mm
Video	ASPEED® AST2600 Integrated 2D Graphic Adapter	Part Numbers	Barebone package (5th/4th Gen): 6NE163S30DR000ABG1* Barebone package (4th Gen): 6NE163S30DR000AAG1* - CPU heatsink: 25ST1-4Z3200-S7R - Mini-DP to D-Sub cable: 25CRN-200801-K1R - Power supply: 25EPO-208503-D0S - 2-Section Rail kit (385-480mm): 25HB2-3A0204-K0R (Optional) - 2-Section Rail kit (660-840mm): 25HB2-3A0203-K0R (Optional)
Storage	Front: 2 x 2.5" Gen4 NVMe/SATA/SAS hot-swappable bays *SAS card is required for SAS devices support 1 x M.2 slot (M-key, PCIe Gen3 x4, supports 2280/22110 cards)		
RAID	Intel® SATA RAID 0/1		
Expansion Slots	2 x FHHL PCIe Gen5 x16 slots 2 x OCP 3.0 Gen5 x16 slots - Supporte NCSI function		
Backplane Board	Speed and bandwidth: PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s		
TPM	1 x TPM header with SPI interface - Optional TPM2.0 kit: CTM010		



Learn more at <https://www.GIGABYTE.com/enterprise>

Designed by



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